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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: : Date: 6/2/2004
Aik Chong Tan et al : Group: 2831
APPLN. NO. 09/736462 : Examiner: Hung V. Ngo
FILED: 12/15/2000 :
FOR: BUMP CHIP LEAD FRAME AND PACKAGE

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS
BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE
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Date of Deposit

SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

Name of Assignee

Lydia McNamara
SIGNATURE

6/3/04
DATE

SUBMITTAL OF FORMAL DRAWINGS

Honorable Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Attn: Official Draftsman

SIR:

We are hereby submitting 5 sheets of replacement formal
drawings for the above-identified patent application.

Respectfully submitted,
Aik Chong Tan et al by

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